

WHAT IS CLAIMED IS:

5

1. A method for mounting an electronic part on a mounting substrate in that projection electrodes provided on said electronic part are welded by fusion to join connection terminals provided on said mounting substrate, said mounting method comprising the steps of:

15 arranging a flux paste on said mounting substrate, said flux paste including a base flux and metal grains having diameters smaller than diameters of said projection electrodes and having a thickness so as to form a space between said flux paste and said electronic part when said electronic part is mounted on said mounting substrate; and

20 sealing a resin in the space formed
between said electronic part and said mounting
substrate after said projection electrodes are joined
to said connection terminals.

25

2. The method as claimed in claim 1,
wherein the diameters of said metal grains are
defined to be more than a tolerance of diameters of
30 said projection electrodes and less than one third
the diameter of said projection electrodes, and
 said flux paste includes said metal grains
more than one percent and less than twenty percent by
volume ratio.

35

3. The method as claimed in claim 1,
wherein said flux paste is arranged on an area having
said connection terminals of said mounting substrate
5 by a thickness being more than the diameters of said
metal grains and less than half the diameters of said
projection electrodes.

10

4. The method as claimed in claim 1,
wherein a base flux of said flux paste includes a
resin used to seal the space as a main constituent.

15

5. The method as claimed in claim 1,
20 wherein a base flux of said flux paste includes a
resin, which is used to seal the space and filler is
eliminated from, as a main constituent.

25

6. The method as claimed in claim 1,
wherein:

30 said projection electrodes have a
spherical shape, and
said metal grains have a shape having a
smooth surface so as to be movable when said
projection electrodes are pressed to said connection
terminals.

35

2020-02-04 13:00:00

7. A method for mounting an electronic part on a mounting substrate in that projection electrodes provided on said electronic part are 5 welded by fusion to join connection terminals provided on said mounting substrate, said mounting method comprising the steps of:

arranging a flux paste on said projection electrodes, said flux paste including metal grains 10 having diameters smaller than diameters of said projection electrodes and having a thickness so as to form a space between said electronic part and said flux paste when said electronic part is mounted on said mounting substrate;

15 joining said projection electrodes to said connection part by mounting said electronic part on said mounting substrate and conducting a heating process; and

sealing a resin in said space formed 20 between said electronic part and said mounting substrate after said projection electrodes are joined to said connection terminals.

25

8. The method as claimed in claim 7, wherein the diameters of said metal grains are defined to be more than a tolerance of the diameters 30 of said projection electrodes and less than one third the diameter of said projection electrodes, and said flux paste includes said metal grains more than one percent and less than twenty percent by volume ratio.

35

9. The method as claimed in claim 7,
wherein a base flux of said flux paste includes a
resin used to seal the space as a main constituent.

5

10. The method as claimed in claim 7,
wherein a base flux of said flux paste includes a
resin, which is used to seal the space and filler is
eliminated from, as a main constituent.

15

11. The method as claimed in claim 7,
wherein:

20 said projection electrodes have a
spherical shape, and

said metal grains have a shape having a
smooth surface so as to be capable of being pushed
outward when said projection electrodes are pressed
to said connection terminals.

25

12. A paste material used to weld by
30 fusion projection electrodes provided on an
electronic part to connection terminals provided on a
mounting substrate, said paste material comprising:

metal grains; and
a base flux,

35 wherein diameters of said metal grains are
defined to be more than a tolerance of diameters of
said projection electrodes and less than one third

the diameter of said projection electrodes, and
said metal grains are included more than
one percent and less than twenty percent by volume
ratio.